

mantis.

Process specifications

PCB dimensions	Max. print area	600x560 mm (23.94x22.83 inches)
	Board thickness	0.2 – 5 mm (0.0079-0.197 inches)
Stencil frame	PCB Edge Clearance (Clamping)	2 mm
	Stencil adapter	Available for most standard stencils
	Stencil frame clamping	Pneumatic clamping, height 25-40 mm (1-1.57 inches)
Transport system	Loading, positioning and ejection	Fully automatic with manual override
	Conveyor extensions	Automatic left for loading, right for unloading
	Board clamping	Pull down foil clamps
	Type	3mm ,D' section polyurethane, single stage belt conveyor
	PCB Edge	Clearance 5mm
	Transport direction	Programmable: Left to Right, R to L, R to R, L to L
	Transport height	900-970 mm (35.43-38.19 inches)
	Maximum underside clearance	25 mm (0.79 inches)
	Substrate max. Weight	max. 3 Kg
SMEMA	SMEMA Standard other protocols available	

Print parameters

Alignment	automatic dual camera vision system
Vision illumination color	programmable red/green/blue LED
Alignment range	+/-10 mm, +/- 2.5 degrees
Cycle time	10 s + print time
Print speed	Programmable, 1-250 mm/sec (0.039-9.84 inches/sec)
Process Alignment Capability	+/-25 μ m @ 6 Sigma Cpk of greater than or equal to 2.0 Based upon actual wet printing with positional accuracy and repeatability verified by a 3rd party measurement system.
Machine Alignment Capability	+/-12.5 μ m @ 6 Sigma Cpk of greater than or equal to 2.0 Qualification is performed using production environment process variables; print speed, table lift and camera movement are included in the capability figure.
Snap Off Speed	Programmable, 0.1 – 20 mm/sec (0.0039-0.79 inches)
Printing pressure	Programmable, 0-20 kg (0.1 kg increments)
Squeegees	Metal or Polyurethane double squeegee, 150-608 mm width, double squeegee, self-leveling (5.9-23.94 inches)
Operation modes	Print, print/print, flood/print, print/flood, 1 or 2 deposits. Others on request